R E M A R K S

Reconsideration of this application, as amended, is respectfully requested.

ALLOWABLE SUBJECT MATTER

The Examiner's indication of the allowability of the subject matter of claims 4, 7 and 9 is respectfully acknowledged.

These claims, however, have not been rewritten in independent form at this time since, as set forth in detail hereinbelow, it is respectfully submitted that their parent claim 1 also recites allowable subject matter.

THE CLAIMS

Claim 1 has been amended to clarify that the resistive layers increase an electric resistance between the arm and each of the magnetic circuit forming members, as supported by the disclosure in the specification at, for example, page 11, line 24 to page 12, line 6.

Claims 1-9 have also been amended to make some minor grammatical improvements and to correct some minor antecedent basis problems so as to put the claims in better form for issuance in a U.S. patent. The informalities pointed out by the Examiner have been corrected.

No new matter has been added, and it is respectfully requested that the amendments to the claims be approved and entered.

THE PRIOR ART REJECTION

Claims 1, 2, 6 and 8 were rejected under 35 USC 103 as being obvious in view of the combination of the Admitted Prior Art and USP 5,074,687 ("Gugel et al"), and claims 3 and 5 were rejected under 35 USC 103 obvious in view of the combination of the Admitted Prior Art, Gugel et al and USP 4,802,776 ("Miyazawa et al"). These rejections, however, are respectfully traversed with respect to the claims as amended hereinabove.

The Examiner acknowledges that the Admitted Prior Art does not disclose resistive layers as recited in claim 1. However, the Examiner contends that the adhesive or cement disclosed by Gugel et al corresponds to the resistive layers of the present invention. More specifically, the Examiner contends that Gugel et al discloses "the use of adhesive or cement as resistivity material for thermal bonding and spot weld" (emphasis added). It is respectfully pointed out, however, that Gugel et al in fact merely discloses performing bonding with an adhesive or cement, and that thermal bonding may also be used. Contrary to the Examiner's assertion, Gugel et al contains no suggestion of increasing resistance for welding. And it is respectfully

submitted that Gugel et al clearly does not disclose, teach or suggest providing layers to increase an electric resistance between the arm and each of the magnetic circuit forming members, as recited in clarified amended independent claim 1.

The Examiner further asserts that if it is argued that Gugel et al does not disclose resistive layers, then the resistive layers of the present invention would be considered an obvious matter of design choice, sine, according to the Examiner, "applicant has not disclosed that these features are critical, patentably distinguishing features."

It is respectfully pointed out, however, that the specification clearly states at page 11, line 24 to page 13, line 2, that:

> The armature manufacturing method of the present invention interposes the resistive layers 50 between the arm 9 and the magnetic circuit forming members 11 to maintain satisfactory contact between the arm 9 and the magnetic circuit forming members 11, and to increase the electrical resistance along the welding current path. Heat is therefore generated in the surfaces joining the arm 9 and magnetic circuit forming members 11 and nuggets are formed in large areas. These large nuggets hold the arm 9 and the magnetic circuit forming members 11 together by high weld strength. Although the arm 9 and the magnetic circuit forming members 11 of the armature 4 are carburized and plated, the arm 9 and the magnetic circuit forming members 11 are held together by high weld strength. The armature 4 will not come apart and will have a long service life.
>
> The nuggets formed by spot-welding the assembly of the arm 9 and the magnetic circuit forming members 11 with the resistive layers 50, as compared with those formed by spot-welding the

> assembly of the arm 9 and the magnetic circuit forming members 11 without the resistive layers 50, can be formed by a low welding current, are large, and have high weld strength. Thus, the assembly of the arm 9 and the magnetic circuit forming members 11 with the resistive layers 50 can be welded together by using a low welding current, which is effective in preventing the distortion of the arm 9 and the magnetic circuit forming members 11. Since the arm 9 and the magnetic circuit forming members 11 are not distorted, the pivot 13 can be smoothly pressed into the end holes 16 after spot welding the arm 9 and the magnetic circuit forming members 11 together.

Thus, it is respectfully submitted that the specification clearly and explicitly states numerous advantages of providing the resistive layers in the manner of the present invention, as opposed to the techniques of the prior art. And it is respectfully submitted that providing the resistive layers in the manner of the present invention is clearly described as a patentably distinguishing feature of the present invention.

Accordingly, it is respectfully submitted that the Examiner's dismissal of the resistive layers of the present invention as an obvious matter of design choice is improper.

In view of the foregoing, it is respectfully submitted that the prior art of record does not disclose, teach or suggest placing magnetic circuit forming members on an arm with a resistive layer of a resistive material sandwiched between the arm and each of the magnetic circuit forming members, wherein the resistive layers increase an electric resistance between the arm

and each of the magnetic circuit forming members, and welding together the arm and the magnetic circuit forming members, with the resistive layers sandwiched between the arm and the magnetic circuit forming members, by spot welding, as recited in clarified amended independent claim 1.

Accordingly, it is respectfully submitted that the present invention as recited in clarified independent claim 1, and claims 2-9 depending therefrom, clearly patentably distinguishes over the admitted prior art, Gugel et al and Miyazawa et al, taken singly or in any combination, under 35 USC 103.

RE: INFORMATION DISCLOSURE STATEMENTS

It is respectfully requested that the Examiner consider the IDS filed on November 2, 2005, and make the references listed thereon of record.

In addition, submitted herewith is an IDS to make of record related U.S. applications and references cited by an Examiner in related applications.

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Entry of this Amendment, allowance of the claims and the passing of this application to issue are respectfully solicited.

If the Examiner has any comments, questions, objections or recommendations, the Examiner is invited to telephone the undersigned at the telephone number given below for prompt action.

Respectfully submitted,

/Douglas Holtz/

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